

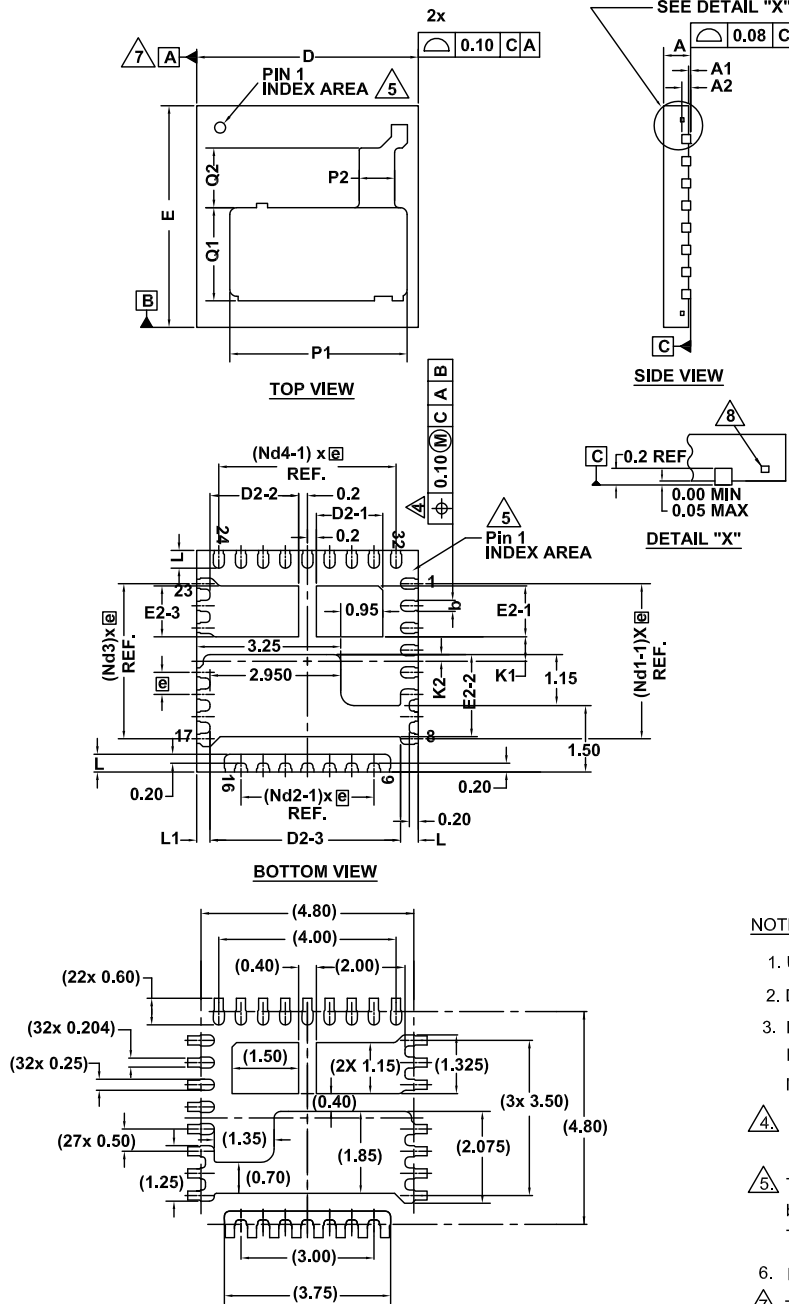
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### L32.5x5V

#### 32 LEAD DOUBLE COOLING QUAD FLAT NO-LEAD PLASTIC PACKAGE

Rev 3 9/17



SYMBOL	MILLIMETERS		
	MIN	NOM	MAX
A (Note 7)	0.56	0.61	0.66
A1	0.00	-	0.05
A2	0.20 REF.		
b (Note 4)	0.20	0.25	0.30
D	5.00 BSC		
D2-1	1.45	1.50	1.55
D2-2	1.95	2.00	2.05
D2-3	4.25	4.30	4.35
e	0.50 BSC		
E	5.00 BSC		
E2-1	1.10	1.15	1.20
E2-2	1.80	1.85	1.90
E2-3	1.10	1.15	1.20
K1	0.55 BSC		
K2	0.15 BSC		
L	0.35	0.40	0.45
L1	0.25	0.30	0.35
P1	3.95	4.00	4.05
P2	0.75	-	1.15
Q1	2.05	2.10	2.15
Q2	1.30	1.35	1.40
N (Note 3)	32		
Nd1 (Note 3)	8 (PIN1~PIN8)		
Nd2 (Note 3)	8 (PIN9~PIN15)		
Nd3 (Note 3)	7 (PIN16~PIN22)		
Nd4 (Note 3)	9 (PIN23~PIN31)		

#### NOTE:

1. Use millimeters as the primary measurement.
2. Dimensioning & tolerances conform to ASME Y14.5M, - 1994.
3. N is the number of terminals.  
Nd1 and Nd3 is the number of terminals in Y-direction &  
Nd2 and Nd4 is the number of terminals in X-direction.
4. Dimension b applies to plated terminal and is measured between 0.20 and 0.25mm from terminal tip.
5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated.  
The pin #1 identifier may be either a mold or mark feature.
6. Package warpage MAX 0.08mm.
7. Tiebar shown (if present) is a non-functional feature.
8. Applied only for terminals.

TYPICAL RECOMMENDED LAND PATTERN